港科内房3040CC,4内村内房3060CC

Data Sheet January 2000 File Number 3939.3

30A, 400V - 600V Hyperfast Dual Diodes

The RHRG3040CC and RHRG3060CC are hyperfast diodes with soft recovery characteristics (t_{rr} < 40ns). They have half the recovery time of ultrafast diodes and are silicon nitride passivated ion-implanted epitaxial planar construction.

These devices are intended for use as freewheeling/ clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits, thus reducing power loss in the switching transistors.

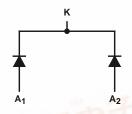
Formerly developmental type TA49063.

Ordering Information

PART NUMBER	PACKAGE	BRAND		
RHRG3040CC	TO-247	RHRG3040C		
RHRG3060CC	TO-247	RHRG3060C		

NOTE: When ordering, use the entire part number.

Symbol



Features

•	Hyperfast with Soft Recovery	<40ns
•	Operating Temperature	175°C
•	Reverse Voltage Up To	.600V

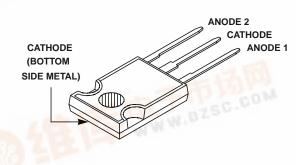
- Avalanche Energy Rated
- · Planar Construction

Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

Packaging

JEDEC STYLE TO-247



Absolute Maximum Ratings (Per Leg) $T_C = 25^{\circ}C$, Unless Otherwise Specified

	RHRG3040CC	RHRG3060CC	UNITS	
Peak Repetitive Reverse VoltageVRRM	400	600	V	
Working Peak Reverse Voltage	400	600	V	
DC Blocking Voltage	400	600	V	
Average Rectified Forward Current $I_{F(AV)}$ ($T_C = 120^{\circ}C$)	30	30	Α	
Repetitive Peak Surge Current	70	70	Α	
Nonrepetitive Peak Surge Current	325	325	Α	
Maximum Power Dissipation	125	125	W	
Avalanche Energy (See Figures 10 and 11)	20	20	mJ	
Operating and Storage Temperature	-65 to 175	-65 to 175	οС	



RHRG3040CC, RHRG3060CC

Electrical Specifications (Per Leg) $T_C = 25^{\circ}C$, Unless Otherwise Specified

		RHRG3040CC		RHRG3060CC				
SYMBOL	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
V _F	I _F = 30A	-	-	2.1	-	-	2.1	V
	I _F = 30A, T _C = 150 ^o C	-	-	1.7	-	-	1.7	V
I _R	V _R = 400V	-	-	250	-	-	-	μА
	V _R = 600V	-	-	-	-	-	250	μА
	V _R = 400V, T _C = 150 ^o C	-	-	1.0	-	-	-	mA
	V _R = 600V, T _C = 150 ^o C	-	-	-	-	-	1.0	mA
t _{rr}	$I_F = 1A$, $dI_F/dt = 200A/\mu s$	-	-	40	-	-	40	ns
	$I_F = 30A$, $dI_F/dt = 200A/\mu s$	-	-	45	-	-	45	ns
t _a	$I_F = 30A$, $dI_F/dt = 200A/\mu s$	-	22	-	-	22	-	ns
t _b	$I_F = 30A$, $dI_F/dt = 200A/\mu s$	-	18	-	-	18	-	ns
Q _{RR}	$I_F = 30A$, $dI_F/dt = 200A/\mu s$	-	100	-	-	100	-	nC
CJ	V _R = 10V, I _F = 0A	-	85	-	-	85	-	pF
$R_{ heta JC}$		-	-	1.2	-	-	1.2	°C/W

DEFINITIONS

 V_F = Instantaneous forward voltage (pw = $300\mu s,\,D$ = 2%).

 I_R = Instantaneous reverse current.

 t_{rr} = Reverse recovery time (See Figure 9), summation of t_a + t_b .

t_a = Time to reach peak reverse current (See Figure 9).

 $t_b = \text{Time from peak I}_{RM} \text{ to projected zero crossing of I}_{RM} \text{ based on a straight line from peak I}_{RM} \text{ through 25\% of I}_{RM} \text{ (See Figure 9)}.$

Q_{RR} = Reverse recovery charge.

 C_J = Junction Capacitance.

 $R_{\theta JC}$ = Thermal resistance junction to case.

pw = pulse width.

D = duty cycle.

Typical Performance Curves

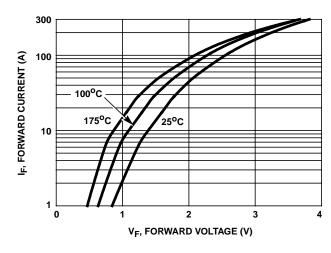


FIGURE 1. FORWARD CURRENT vs FORWARD VOLTAGE

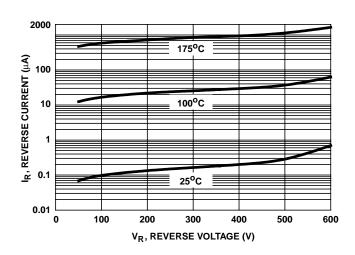


FIGURE 2. REVERSE CURRENT vs REVERSE VOLTAGE

RHRG3040CC, RHRG3060CC

Typical Performance Curves (Continued)

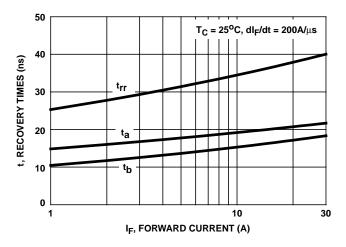


FIGURE 3. t_{rr} , t_a and t_b curves vs forward current

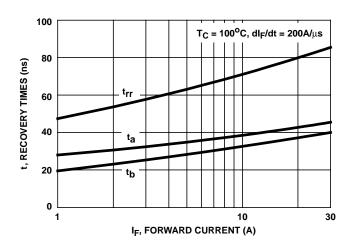


FIGURE 4. t_{rr} , t_a and t_b curves vs forward current

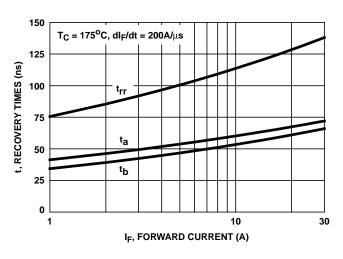


FIGURE 5. t_{rr} , t_a and t_b curves vs forward current

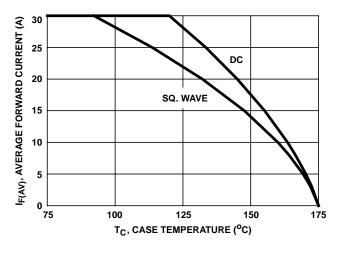


FIGURE 6. CURRENT DERATING CURVE

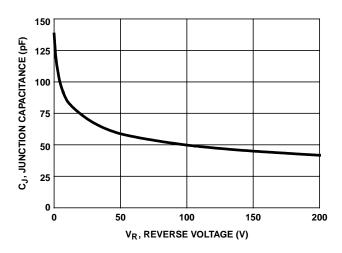


FIGURE 7. JUNCTION CAPACITANCE vs REVERSE VOLTAGE

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RHRG3040CC, RHRG3060CC

Test Circuits and Waveforms

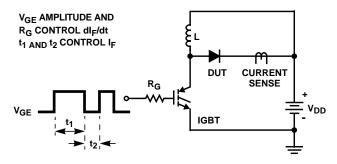


FIGURE 8. t_{rr} TEST CIRCUIT

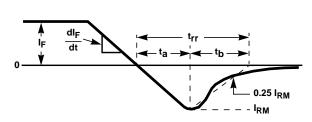


FIGURE 9. t_{rr} WAVEFORMS AND DEFINITIONS

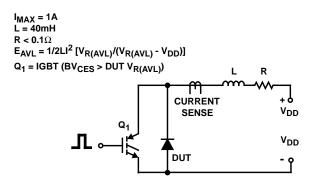


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

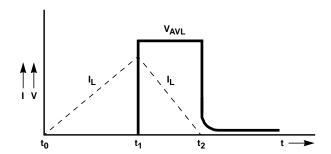


FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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